

REV.	ECN NO	DESCRIPTION	DATE	DRAW	APPR
A		NEW			

1)MATERIAL:

HOUSING: LCP UL 94V-0
CONTACT: C5210R-H,T=0.15
SHELL: SUS201,T=0.20
MYLAR: POLYESTER

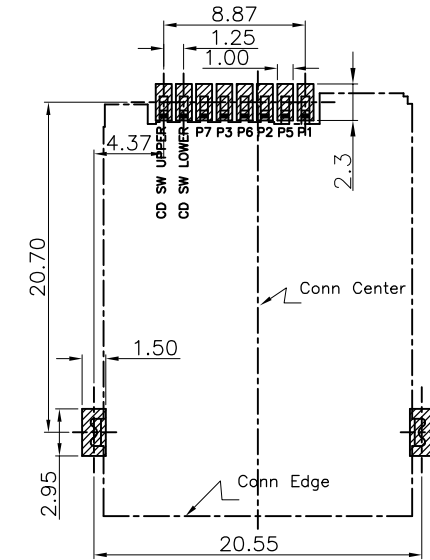
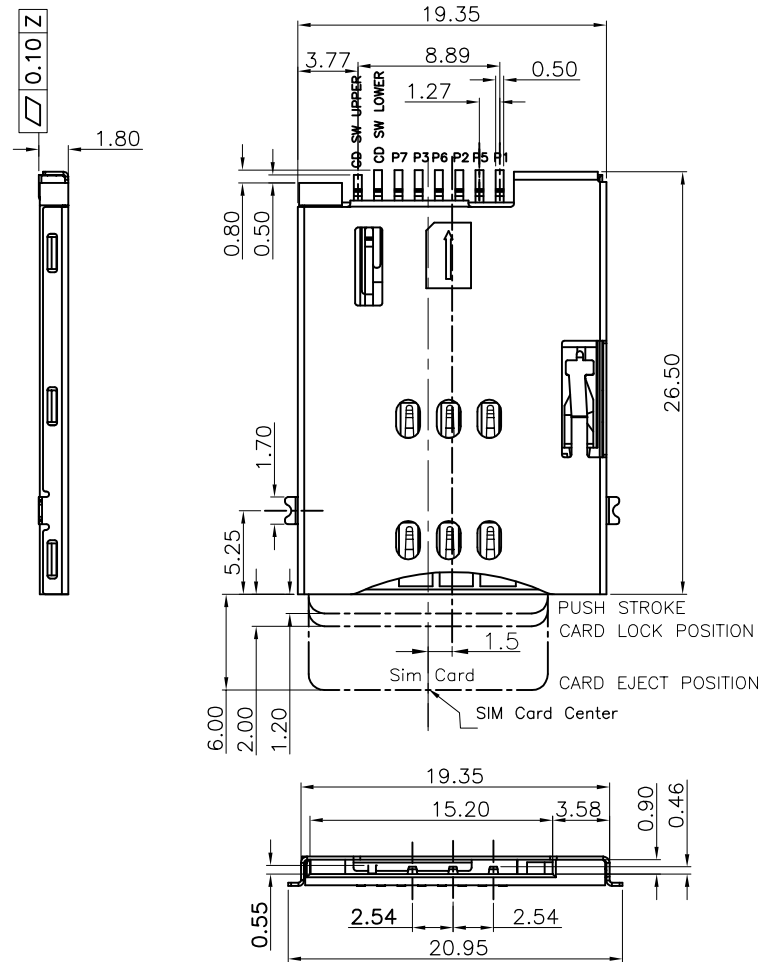
2)FINISH :

CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATING ON SOLDER TAILS, WITH
ENTIRE CONTACT UNDERPLATED 50u"Min. NICKEL
SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL ,
GOLD FLASH PLATED ON SOLDER TAILS

3.INFRAED REFLOW SOLDERING: 10sec. Min. at 260^{+10}_0

4.PART NO:

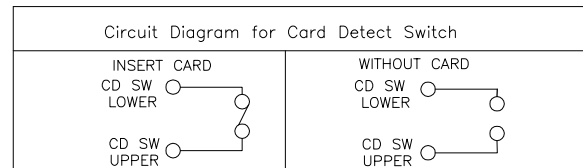
SMPT08-C0-0180 WITHOUT LOGO
SMPT08-C0-G180 WITH LOGO "GCONN"



RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

- SOLDER AREA
- NONE CIRCUIT DIAGRAM AREA

CONNECTOR TERMINAL NO	PIN NO
PIN 1	VCC:PWR SIGNAL AND GND
PIN 2	RST:RESET SIGNAL
PIN 3	CLK:CLOCKING SIGNAL
PIN 5	GND:PWR SIGNAL AND GND
PIN 6	VPP:PROGRAMMING VOLTAGE
PIN 7	I/O:SERIAL DATA INPUT/OUTPUT



		CIXI YEXIN ELECTRONICS FACTORY			
Drawn		Tolerance Unless Otherwise Specified		Title: SIM PUSH 6+2 Without Post	
Checked		± 0.25	$\pm 3'$	Part No.: SMPT08-C0-X180	
		$.X \pm 0.15$	$.X' \pm 2'$		
Approval		$.XX \pm 0.10$	$.XX' \pm 1'$		Sheet 1/1 Rev A
		$.XXX \pm 0.05$			
		www.yexin.net			